



WLCSP16 1.56x1.56x0.29, 0.40P CASE 567UX **ISSUE A**

DATE 31 MAY 2024

NOTES:

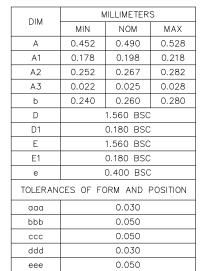
- DIMENSIONING AND TOLERANCING CONFORM TO ASME
- 714.5M-2018.

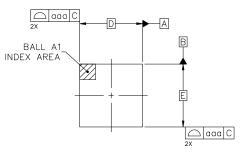
 ALL DIMENSIONS ARE IN MILLIMETERS.

 DIMENSION & IS MEASURED AT THE MAXIMUM SOLDER

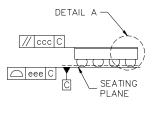
 BALL DIAMETER PARALLEL TO DATUM C.

 COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF
- THE SOLDER BALLS.
- DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

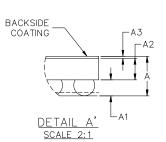


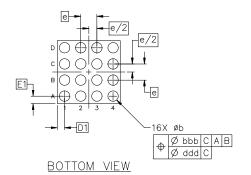


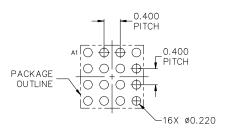
TOP VIEW



SIDE VIEW







RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

XXXXX XXXXX **AYYWW**

XXXX = Specific Device Code = Assembly Location

= Year WW = Work Week *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON87373G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	WLCSP16 1.56x1.56x0.29, 0.40P		PAGE 1 OF 1

onsemi and Onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries, onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.